

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination	
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		Examiner	Art Unit	Page 1 of 1
		David Y Jung	2134	

U.S. PATENT DOCUMENTS

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*	Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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